

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

TANAKA, et al.

Serial No: 10/537,959

Filed: June 7, 2005

For: Thermoplastic Polyimide Resin
Film, Multilayer Body and
Method for Manufacturing
Printed Wiring Board Composed
of Same

Art Unit: 1796

Conf. No.: 1391

Examiner: Gregory Listvoyb

RESPONSE TO RESTRICTION REQUIREMENT

Mail Stop Non-Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Restriction Requirement dated August 4, 2008, Applicants elect for prosecution Group III, claims 12-15, without traverse.

If there are any fees due in connection with the filing of this response, please charge the fees to our Deposit Account No. 50-1314.

Respectfully submitted,

HOGAN & HARTSON L.L.P.

Date: November 11, 2008

By: 

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